



Institute of Electrical and Electronics Engineers, Inc.



IEEE Phoenix Section Components, Packaging and Manufacturing Technology Society Chapter & Waves and Devices Chapter

PRESENT AN ALL-DAY WORKSHOP ON

Images courtesy of; Occam Services; Mondolithic Studios www.mondolithic.com; Prof. Belcher, Prof. Chiang and Prof. Hammond (MIT)

Emerging Device and Packaging Technologies *Sense, Compute, and Communicate*

Friday, November 19, 2010 7:00 A.M. – 5:00 P.M.

Arizona State University, Tempe, Arizona – ASU Memorial Union (Arizona Room)

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Call for Papers

The combination of technologies required to address societal grand challenges in areas such as energy, health, and security necessitates the creation of systems that have far-reaching abilities to **sense, compute, and communicate**. Such systems vary in complexity, from basic home networks to much more sophisticated remote health, security monitoring, and satellite systems, and can involve fields as diverse as biochemical sensing, ad-hoc networks, low-power/high-performance computing, and planetary surface science. This year's one-day workshop will focus on the 'sense, compute, and communicate' topic and will pull together experts from industry, academia, research labs, and consortia to share their vision of technical challenges and opportunities in these areas. A poster session will be featured on the broader workshop topic of emerging device and packaging technologies and select vendors will exhibit products and services related to all aspects of the supply chain for design and manufacturing.

Invited Speaker Topics

Portable Electronics

- Urban/Participatory Sensing
- MEMS/BioMEMS
- Low-Power Compute/Communicate
- Advanced Portable Electronics Packaging

Space Systems

- Planetary Surface Studies
- Optical Crosslinks
- Software-Programmable Space Radios
- Low-Power Compute/Communicate

Poster Session

Abstracts are invited for consideration to the poster session in emerging device and packaging technologies (and not limited to the topics sense, compute, or communicate).

Poster Abstract Submissions: Two pages (topic, summary of significant results and conclusions – WORD or PDF files only). Abstract must include author names, affiliations, addresses, and e-mail address of lead author.

Submission Deadline:	September 15, 2010
Submitting Address:	mel.miller@ieee.org
Acceptance Notification:	October 1, 2010
Final Presentation Due:	November 5, 2010

Sponsorships and Vendor Displays: This is a great opportunity to promote your company or product. For more information, contact Vasu Atluri vpatluri@ieee.org, Steve Rockwell steve.rockwell@ieee.org, or Vivek Gupta vivek.gupta@freescale.com

Workshop Registration: On-line registration will open in August at www.acteva.com/go/ieeephxsecworkshop2010